

## In the Claims

Claims 1-67 and 69-88 are canceled.

Cancel claim 68.

✓ 89. [New] A method of processing a wafer comprising:  
receiving a wafer within a workpiece processing apparatus;  
supporting the wafer using a workpiece holder of the workpiece processing apparatus;  
coupling circuitry of the wafer with circuitry of the workpiece holder;  
processing the wafer within the workpiece processing apparatus to form at least one semiconductor device; and  
communicating signals intermediate the circuitry of the wafer and the circuitry of the workpiece holder.

✓ 90. [New] The method in accordance with claim 89 wherein the coupling comprises coupling the circuitry of the wafer and the circuitry of the workpiece holder at a surface of the wafer and a surface of the workpiece holder.

✓ 91. [New] The method in accordance with claim 89 wherein the receiving comprises receiving a semiconductive wafer.

92. [New] The method in accordance with claim 89 further comprising altering the processing responsive to the communicating.

✓ 93. [New] The method in accordance with claim 89 wherein the communicating comprises communicating during the processing.

✓ 94. [New] The method in accordance with claim 89 further comprising communicating the signals using an intermediate member of the workpiece processing apparatus.

✓ 95. [New] The method in accordance with claim 89 wherein the coupling comprises contacting the circuitry of the wafer and the circuitry of the workpiece holder.

✓ 96. [New] The method in accordance with claim 89 wherein the communicating comprises communicating the signals comprising information.

97. [New] The method in accordance with claim 89 wherein the communicating comprises communicating the signals comprising information regarding the processing.

✓ 98. [New] A method of processing a workpiece comprising:  
receiving a workpiece within a workpiece processing apparatus configured to form a semiconductor device using the workpiece;  
processing the workpiece within the workpiece processing apparatus to form the semiconductor device; and  
communicating signals intermediate the workpiece and the workpiece processing apparatus.

✓ 99. [New] The method in accordance with claim 98 further comprising electrically coupling the workpiece and the workpiece processing apparatus.

100. [New] The method in accordance with claim 99 wherein the coupling comprises contacting circuitry of the workpiece and circuitry of the apparatus.

✓ 101. [New] The method in accordance with claim 98 further comprising:  
supporting a workpiece using a workpiece holder of the workpiece processing apparatus; and

coupling circuitry of the workpiece and circuitry of the workpiece holder at a surface of the workpiece and a surface of the workpiece holder.

✓ 102. [New] The method in accordance with claim 98 wherein the receiving comprises receiving the workpiece comprising a semiconductive wafer.

103. [New] The method in accordance with claim 98 further comprising altering the processing responsive to the communicating.

✓ 104. [New] The method in accordance with claim 98 wherein the communicating comprises communicating during the processing.

✓ 105. [New] The method in accordance with claim 98 further comprising communicating the signals using an intermediate member of the workpiece processing apparatus.

✓ 106. [New] The method in accordance with claim 98 wherein the communicating comprises communicating the signals comprising information.

107. [New] The method in accordance with claim 98 wherein the communicating comprises communicating the signals comprising information regarding the processing.

✓ 108. [New] A method of communicating signals with respect to a wafer comprising:

providing a workpiece holder;  
supporting a wafer using the workpiece holder;  
coupling circuitry of the wafer with circuitry of the workpiece holder; and  
communicating signals intermediate the circuitry of the wafer and the circuitry of the workpiece holder.

109. [New] The method in accordance with claim 108 wherein the providing the wafer comprises providing a semiconductive wafer.

110. [New] The method in accordance with claim 108 wherein the coupling comprises coupling the circuitry of the wafer and the circuitry of the workpiece holder at a surface of the wafer and a surface of the workpiece holder.

111. [New] The method in accordance with claim 108 wherein the coupling comprises contacting the circuitry of the wafer and the circuitry of the workpiece holder.

112. [New] The method in accordance with claim 108 wherein the communicating comprises communicating using an intermediate member.

113. [New] The method in accordance with claim 108 wherein the communicating comprises communicating the signals comprising information.

114. [New] The method in accordance with claim 108 wherein the communicating comprises communicating the signals comprising information regarding processing of the wafer.

115. [New] A method of communicating signals within a workpiece processing apparatus comprising:

providing a workpiece processing apparatus adapted to process a workpiece to form a semiconductor device;

providing a workpiece within the workpiece processing apparatus;

*pdw* communicating signals using the workpiece; and

receiving the signals within the workpiece processing apparatus from the workpiece.

✓ 116. [New] The method in accordance with claim 115 further comprising coupling circuitry of the workpiece with circuitry of the workpiece processing apparatus.

✓ 117. [New] The method in accordance with claim 116 wherein the coupling comprises contacting the circuitry of the workpiece with the circuitry of the workpiece processing apparatus.

? 118. [New] The method in accordance with claim 116 further comprising breaking the coupling of the circuitry of the workpiece and the circuitry of the workpiece processing apparatus.

✓ 119. [New] The method in accordance with claim 115 further comprising supporting the workpiece within the workpiece processing apparatus using a workpiece holder, and wherein the receiving comprises receiving using the workpiece holder.

✓ 120. [New] The method in accordance with claim 119 further comprising coupling circuitry of the workpiece and circuitry of the workpiece holder at a surface of the workpiece and a surface of the workpiece holder.

✓ 121. [New] The method in accordance with claim 115 further comprising supporting the workpiece within the workpiece processing apparatus using a workpiece holder and an intermediate member, and wherein the receiving comprises receiving using the workpiece holder and the intermediate member.

✓ 122. [New] The method in accordance with claim 115 wherein the providing the workpiece comprises providing a semiconductive wafer.

✓ 123. [New] The method in accordance with claim 115 wherein the communicating comprises communicating the signals comprising information.

124. [New] The method in accordance with claim 115 wherein the communicating comprises communicating the signals comprising information regarding processing of the workpiece.